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PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE



In re Application of:
LARRY ZHAO
JEREMY MARTIN
HARTMUT RUELKE

Serial No.: 10/717,122

Filed: November 19, 2003

For: DIELECTRIC BARRIER LAYER FOR A
COPPER METALLIZATION LAYER
HAVING A VARYING SILICON
CONCENTRATION ALONG ITS
THICKNESS

Examiner: Alexander G. Ghyka

Group Art Unit: 2812

Att'y Docket: 2000.106900/DE0130

Customer No.: 23720

RESPONSE TO OFFICE ACTION DATED AUGUST 10, 2005

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

CERTIFICATE OF MAILING 37 C.F.R. 1.8	
I hereby certify that this correspondence is being deposited with the U.S. Postal Service with sufficient postage as First Class Mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on the date below:	
October 27, 2005 Date	<i>Mary Paul</i> Signature

This paper is submitted in response to the Office Action dated August 10, 2005, for which the three-month date for response is November 10, 2005.

No fees are believed to be due in connection with the present paper. However, should any fees be required under 37 C.F.R. §§ 1.16 to 1.21, the Director is authorized to deduct such fees from the Advanced Micro Devices, Inc. Deposit Account No. 01-0365/DE0130.¹

Reconsideration of the application in view of the following amendments and remarks is respectfully requested.

¹ In the event the monies in that account are insufficient, the Director is authorized to withdraw funds from Williams, Morgan & Amerson, P.C. Deposit Account No. 50-0786/2000.106900.